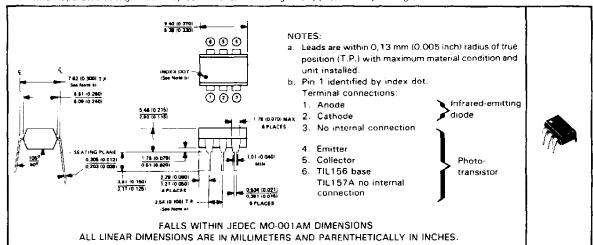
### UL LISTED - FILE #E65085

- GaAs-Diode Light Source Optically Coupled to a Silicon N-P-N Darlington-Connected Phototransistor
- High Direct-Current Transfer Ratio . . . 300% Minimum at 10 mA
- Plug-In Replacement for TIL113 and TIL119A
- High-Voltage Electrical Isolation . . . 2500 V RMS (3535 V Peak)
- No Base Connection on TIL157A for Environments with High Electromagnetic Interference

#### mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon darlington-connected phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high humidity conditions. Unit weight is approximately 0.52 grams.



### absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output RMS Voltage (See Note 1)	2500 V
Collector-Base Voltage (TIL156)	30 V
Collector-Emitter Voltage (See Note 2)	30 V
Emitter-Collector Voltage	7 V
Emitter-Base Voltage (TIL156)	7 V
Input-Diode Reverse Voltage	3 V
Input-Diode Continuous Forward Current at (or below) 25°C Free-Air Temperature (See Note 3)	100 mA
Continuous Phototransistor Power Dissipation at (or below) 25°C Free-Air Temperature (See Note 4)	
Storage Temperature Range	150°C
Lead Temperature 1,6 mm (1/16 inch) from Case for 10 Seconds	

- NOTES 1. This rating applies for sine-wave operation at 50 or 60 Hz. Service capability is verified by testing in accordance with UL requirements.
  - 2. This value applies when the base emitter diode is open-circuited.
  - 3. Denate linearly to 100°C free-air temperature at the rate of 1.33 mA/°C.
  - 4. Denate linearly to 100°C free-air temperature at the rate of 2 mW/°C.



# TIL158, TIL157A OPTOCOUPLERS

# electrical characteristics at 25°C free-air temperature

PARAMETER		TEST CONDITIONS†			TIL156			TIL157A			UNIT		
					MIN T	TYP	MAX	MIN	TYP	MAX	UNIT		
V(BR)CBO	Collector-Base Breakdown Voltage	I <sub>C</sub> = 10 μA,	I <sub>E</sub> = 0,	IF = 0	30						٧		
V(BR)CEO	Collector-Emitter Breakdown Voltage	IC = 1 mA,	(g = 0,	IF=0	30			30			<b>v</b>		
V(BR)EBO	Emitter-Base Breakdown Voltage	ig = 10 μA,	IC = 0.	1F = 0	7						v		
V(BR)ECO	Emitter-Collector Breakdown Voltage	IE = 10 μA,	le * 0					7			v		
l <sub>A</sub>	Input Diade Static Reverse Current	V <sub>R</sub> = 3 V					10			10	μА		
<sup>†</sup> C(on)	On-State	V <sub>CE</sub> = 1 V,	lg = 0,	IF = 10 mA	30	100					mA		
	Collector Current	V <sub>CE</sub> = 1 V,	1 <sub>F</sub> = 10 mA		<u> </u>			30	160				
<sup> </sup> C(off)	Off-State Collector Current	V <sub>CE</sub> = 10 V,	1g = 0,	1F = 0			100			100	nA		
hFE	Transistor Static Forward Current Transfer Ratio	V <sub>CE</sub> = 1 V,	IC = 10 mA,	IF = 0		15 000							
٧F	Input Diode Static Forward Voltage	I <sub>F</sub> = 10 mA					1.5			1.5	V		
	Collector-Emitter	Ic = 125 mA,	i <sub>B</sub> = 0,	1 <sub>F</sub> = 50 mA			1.2				v		
VCE(sat)	Saturation Voltage	IC = 30 mA,	IF = 10 mA		1					1			
10	Input-to-Output Internal Resistance	V <sub>in-out</sub> = 500 V,	See Note 5		1011			1011			Ω		
c <sub>io</sub>	Input-to-Output Capacitance	V <sub>in-out</sub> * 0,	f = 1 MHz,	See Note 5		1	1.3		1	1.3	pF		

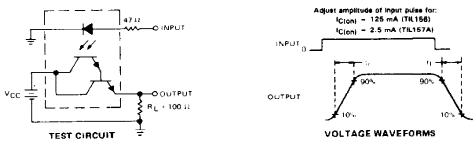
Note 5: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together.

†References to the base are not applicable to the TIL157A.

### switching characteristics at 25°C free-air temperature

PARAMETER					TIL156			TIL157A			
		TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
tr	Rise Time	V <sub>CC</sub> = 15 V,	IC(on) = 125 mA,		300	300					
t <sub>f</sub>	Fall Time	R <sub>L</sub> = 100 Ω.	See Figure 1		300				-	μs	
tr	Rise Time	V <sub>CC</sub> = 10 V,	I <sub>Clon)</sub> = 2.5 mA.				ľ	300			
ty	Fall Time	R <sub>L</sub> = 100 Ω.	See Figure 1					300		<u>ک</u> لز -	

### PARAMETER MEASUREMENT INFORMATION



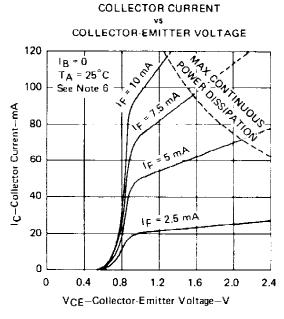
NOTES: a. The input waveform is supplied by a generator with the following characteristics:  $Z_{\text{out}} \sim 50 \, \Omega_c$ ,  $\tau_r \approx 15 \, \text{ns}$ , duty cycle  $\approx 1\%$ ,

FIGURE 1-SWITCHING TIMES

 $t_W=500~\mu s$ . b. The output waveform is monitored on an oscilloscope with the following characteristics:  $\tau_r \le 12$  ns,  $R_{in} \ge 1$  MSS,  $C_{in} \le 20$  pF.

TEXAS INSTRUMENTS

### TYPICAL CHARACTERISTICS



**COLLECTOR CURRENT COLLECTOR-EMITTER VOLTAGE** 200 180 160 1F = 30 mA IC-Collector Current-mA 140 = 40 mA 120 | F = 50 mA 100 80 60 40 1<sub>B</sub> = 0  $T_A = 25^{\circ}C$ 20 See Note 6 0 0.2 0.4 0.6 0.8 1 1.2 1.4 1.6 1.8 2 VCE-Collector-Emitter Voltage-V

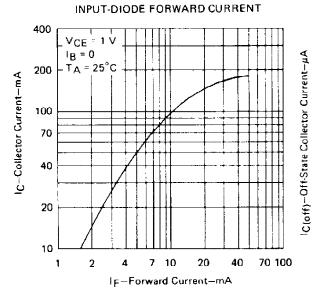
FIGURE 2

COLLECTOR CURRENT





FIGURE 3



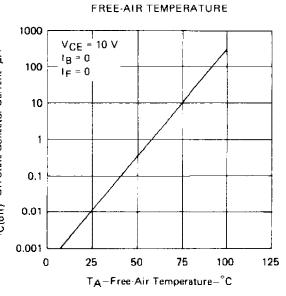


FIGURE 4

FIGURE 5

NOTE 6. Pulse operation of input diode is required for operation beyond limits shown by dotted line,

# TYPICAL CHARACTERISTICS

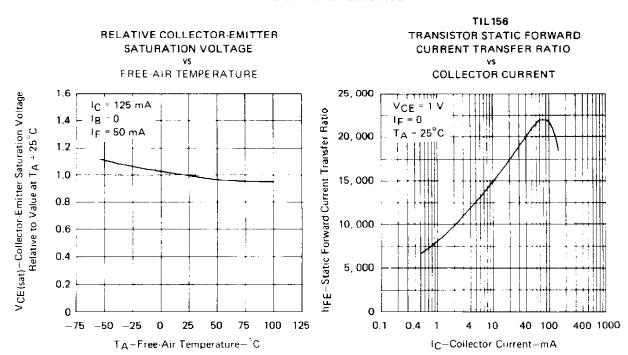
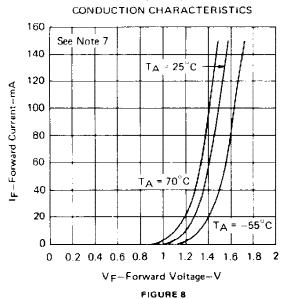


FIGURE 6
INPUT DIODE FORWARD



NOTE 7: This parameter was measured using pulse techniques,  $t_{\rm W} = 1~{\rm ms}$ , duty cycle  $\leq 2\%$ .

FIGURE 7

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